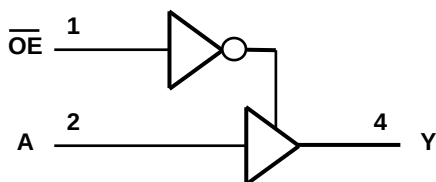


Pin Descriptions

Pin Name	Description
$\overline{OE}$	Output Enable (active low)
A	Data Input
GND	Ground
Y	Data Output
Vcc	Supply Voltage

Logic Diagram



Function Table

Inputs		Output
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

Absolute Maximum Ratings (Note 3)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to 6.5	V
V_I	Input Voltage Range	-0.5 to 6.5	V
V_O	Voltage applied to output in high impedance or I_{OFF} state	-0.5 to 6.5	V
V_O	Voltage applied to output in high or low state	-0.3 to $V_{CC} + 0.5$	V
I_{IK}	Input Clamp Current $V_I < 0$	-50	mA
I_{OK}	Output Clamp Current	-50	mA
I_O	Continuous output current	± 50	mA
	Continuous current through Vdd or GND	± 100	mA
T_J	Operating Junction Temperature	-40 to 150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature	-65 to 150	$^{\circ}\text{C}$

Note: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 4)

Symbol	Parameter		Min	Max	Unit
V _{CC}	Operating Voltage	Operating	1.4	5.5	V
		Data retention only	1.2		V
V _{IH}	High-level Input Voltage	V _{CC} = 1.4 V to 1.95 V	0.65 X V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 3 V to 3.6 V	2		
		V _{CC} = 4.5 V to 5.5 V	0.7 X V _{CC}		
V _{IL}	Low-level input voltage	V _{CC} = 1.4 V to 1.95 V		0.35 X V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V		0.7	
		V _{CC} = 3 V to 3.6 V		0.8	
		V _{CC} = 4.5 V to 5.5 V		0.3 X V _{CC}	
V _I	Input Voltage		0	5.5	V
V _O	Output Voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} =1.4 V		-3	mA
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
		V _{CC} = 3 V		-16	
				-24	
		V _{CC} = 4.5 V		-32	
I _{OL}	Low-level output current	V _{CC} =1.4 V		3	mA
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
		V _{CC} = 3 V		16	
				24	
		V _{CC} = 4.5 V		32	
Δt/ΔV	Input transition rise or fall rate	V _{CC} = 1.4 to 3V		20	ns/V
		V _{CC} = 3.3 V ± 0.3 V		10	
		V _{CC} = 5 V ± 0.5 V		5	
T _A	Operating free-air temperature		-40	85	°C

Note: 4. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = 25^\circ C$)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	Test Conditions	Vcc	Min	Typ.	Max	Unit
V_{OH}	High Level Output Voltage	$I_{OH} = -100\mu A$	1.4 V to 5.5V	$V_{CC} - 0.1$			V
		$I_{OH} = -3mA$	1.4 V	1.05			
		$I_{OH} = -4mA$	1.65 V	1.2			
		$I_{OH} = -8mA$	2.3V	1.9			
		$I_{OH} = -16mA$	3 V	2.4			
		$I_{OH} = -24mA$		2.3			
		$I_{OH} = -32mA$	4.5 V	3.8			
V_{OL}	High-level Input Voltage	$I_{OL} = 100\mu A$	1.4 V to 5.5V			0.1	V
		$I_{OL} = 3mA$	1.4V			.4	
		$I_{OL} = 4mA$	1.65 V			0.45	
		$I_{OL} = 8mA$	2.3V			0.3	
		$I_{OL} = 16mA$	3 V			0.4	
		$I_{OL} = 24mA$				0.55	
		$I_{OL} = 32mA$	4.5			0.55	
I_I	Input Current	$V_I = 5.5 V$ or GND	0 to 5.5 V			± 5	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5V$	0			± 10	μA
I_{OZ}	Z State Leakage Current	$V_O = 0$ to 5.5V	3.6V			10	μA
I_{CC}	Supply Current	$V_I = 5.5V$ of GND $I_O = 0$	1.4 V to 5.5V			10	μA
ΔI_{CC}	Additional Supply Current	One input at $V_{CC} - 0.6 V$ Other inputs at V_{CC} or GND	3 V to 5.5V			500	μA
C_i	Input Capacitance	$V_i = V_{CC} -$ or GND	3.3		3.5		pF
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT25	(Note 5)		204		$^\circ C/W$
		SOT353	(Note 5)		371		
		DFN1410	(Note 5)		430		
θ_{JC}	Thermal Resistance Junction-to-Case	SOT25	(Note 5)		52		$^\circ C/W$
		SOT353	(Note 5)		143		
		DFN1410	(Note 5)		190		

Note: 5. Test condition for SOT25, SOT353 and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

Over recommended free-air temperature range, $C_L = 15\text{pF}$ (see Figure 1)

Parameter	From (Input)	TO (OUTPUT)	Vcc = 1.5 V ± 0.1V		Vcc = 1.8 V ± 0.15V		Vcc = 2.5 V ± 0.2V		Vcc = 3.3 V ± 0.3V		Vcc = 5 V ± 0.5V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.9	6.9	1.3	4.8	0.5	3.6	0.4	3	0.4	3	ns

Over recommended free-air temperature range, $C_L = 30$ or 50pF as noted (see Figure 2)

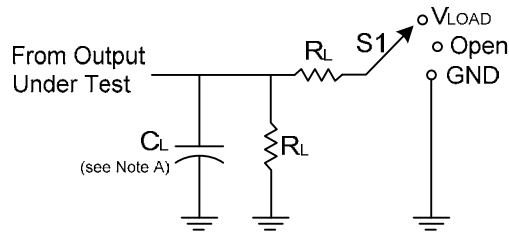
Parameter	From (Input)	TO (OUTPUT)	Vcc = 1.5 V ± 0.1V		Vcc = 1.8 V ± 0.15V		Vcc = 2.5 V ± 0.2V		Vcc = 3.3 V ± 0.3V		Vcc = 5 V ± 0.5V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	2.8	9	1.9	6.3	0.9	4.4	0.8	3.6	0.9	3.6	ns
t_{en}	$\overline{\text{OE}}$	Y	3.3	10.1	2.3	7	1.2	5.2	0.8	4.3	0.9	4.5	
t_{dis}	$\overline{\text{OE}}$	Y	1.3	9.2	0.9	6.4	0.8	4	0.8	4.1	0.9	3.7	

Operating Characteristics

$T_A = 25^\circ\text{C}$

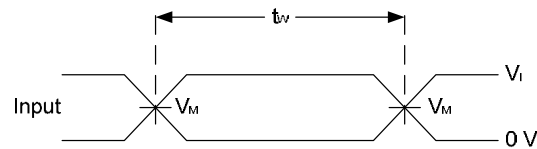
Parameter			Test Conditions	Vcc = 1.5 V	Vcc = 1.8 V	Vcc = 2.5 V	Vcc = 3.3 V	Vcc = 5 V	Unit
				TYP	TYP	TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	Outputs enabled	$f = 10\text{ MHz}$	20	20	20	21	22	pF
		Outputs disabled		2	2	2	2	4	

Parameter Measurement Information

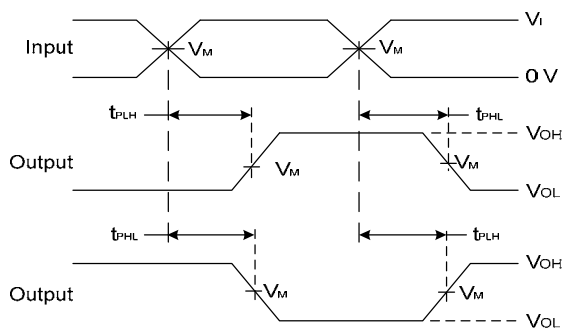


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

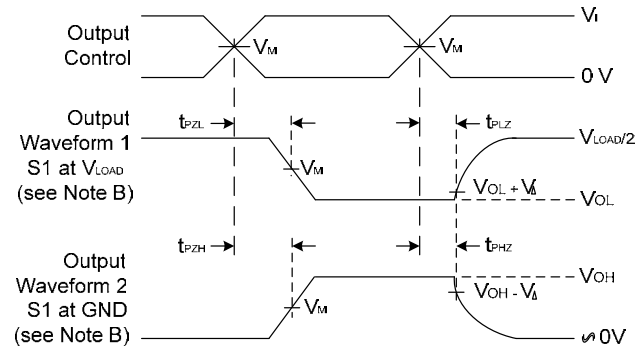
V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_r/t_f			
$1.5V \pm 0.1V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	15pF	1M Ω
$1.8V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	15pF	1M Ω
$2.5V \pm 0.2V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	15pF	1M Ω
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	15pF	1M Ω
$5V \pm 0.5V$	V_{CC}	$\leq 2.5ns$	$V_{CC}/2$	15pF	1M Ω



Voltage Waveform Pulse Duration



**Voltage Waveform Propagation Delay Times
Inverting and Non Inverting Outputs**

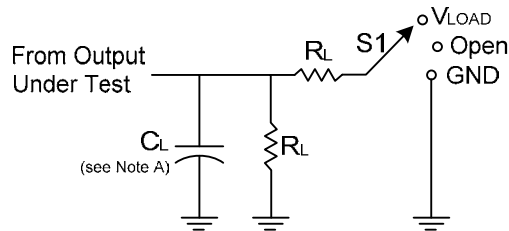


**Voltage Waveform Enable and Disable Times
Low and High Level Enabling**

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - E. t_{PZL} and t_{PZH} are the same as t_{EN} .
 - F. t_{PLH} and t_{PHL} are the same as t_{PD} .

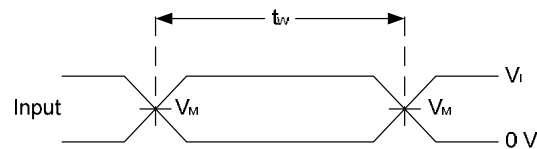
Figure 1. Load Circuit and Voltage Waveforms

Parameter Measurement Information (Continued)

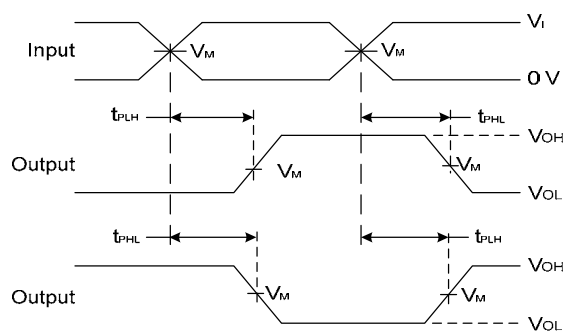


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

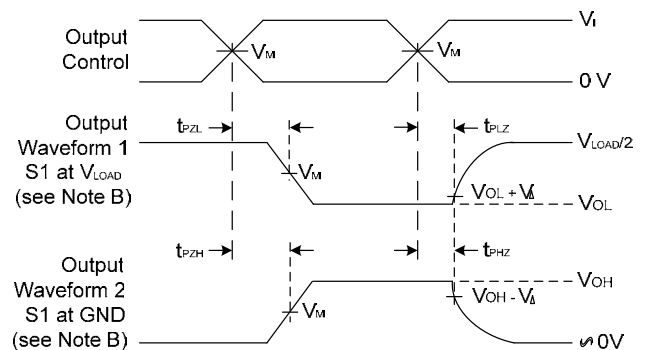
V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_r/t_f			
$1.5V \pm 0.1V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	30pF	1K Ω
$1.8V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	30pF	1K Ω
$2.5V \pm 0.2V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	30pF	500 Ω
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	50pF	500 Ω
$5V \pm 0.5V$	V_{CC}	$\leq 2.5ns$	$V_{CC}/2$	50pF	500 Ω



Voltage Waveform Pulse Duration



**Voltage Waveform Propagation Delay Times
Inverting and Non Inverting Outputs**

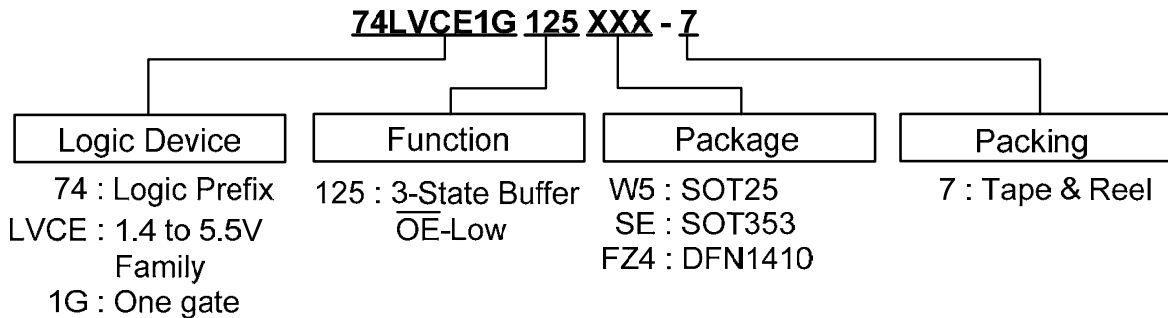


**Voltage Waveform Enable and Disable Times
Low and High Level Enabling**

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - E. t_{PZL} and t_{PZH} are the same as t_{EN0} .
 - F. t_{PLH} and t_{PHL} are the same as t_{PD} .

Figure 2. Load Circuit and Voltage Waveforms

Ordering Information



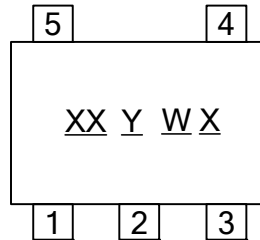
Device	Package Code	Packaging (Note 5)	7" Tape and Reel	
			Quantity	Part Number Suffix
74LVCE1G125W5-7	W6	SOT25	3000/Tape & Reel	-7
74LVCE1G125SE-7	SE	SOT353	3000/Tape & Reel	-7
74LVCE1G125FZ4-7	FZ4	DFN1410	5000/Tape & Reel	-7

Note: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

Marking Information

(1) SOT25 and SOT353

(Top View)



XX : Identification code

Y : Year 0~9

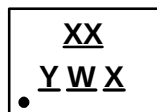
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week

X : A~Z : Internal code

Part Number	Package	Identification Code
74LVCE1G125W5	SOT25	PY
74LVCE1G125SE	SOT353	PY

(2) DFN1410

(Top View)



XX : Identification Code

Y : Year : 0~9

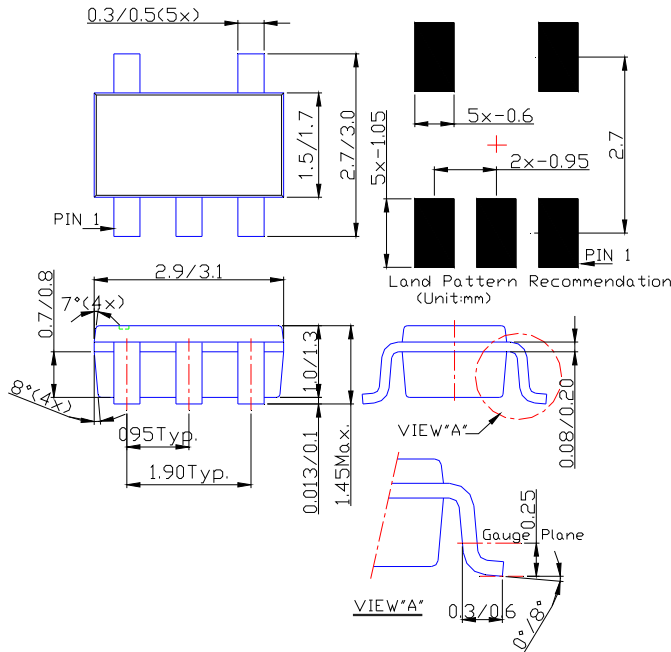
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week

X : A~Z : Internal code

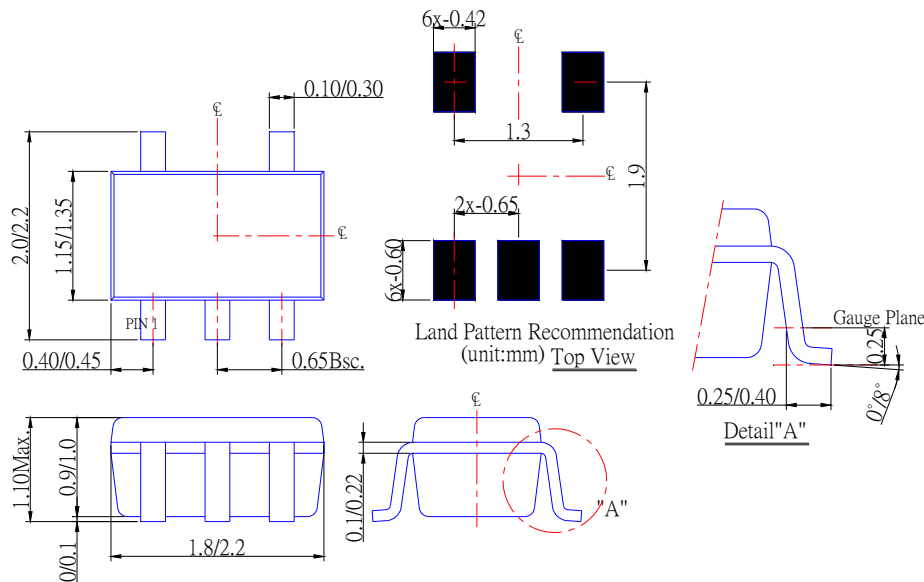
Part Number	Package	Identification Code
74LVCE1G125FZ4	DFN1410	PY

Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25

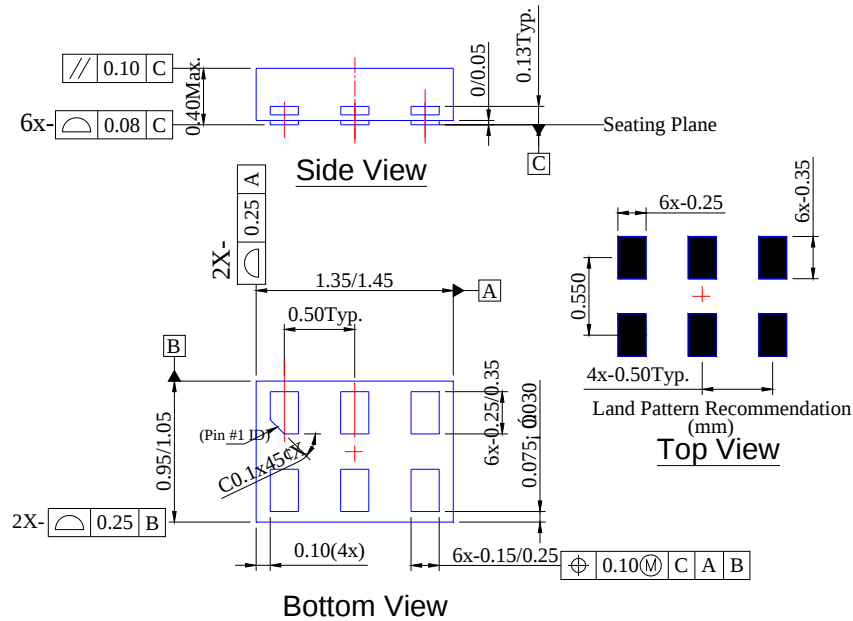


(2) Package Type: SOT353



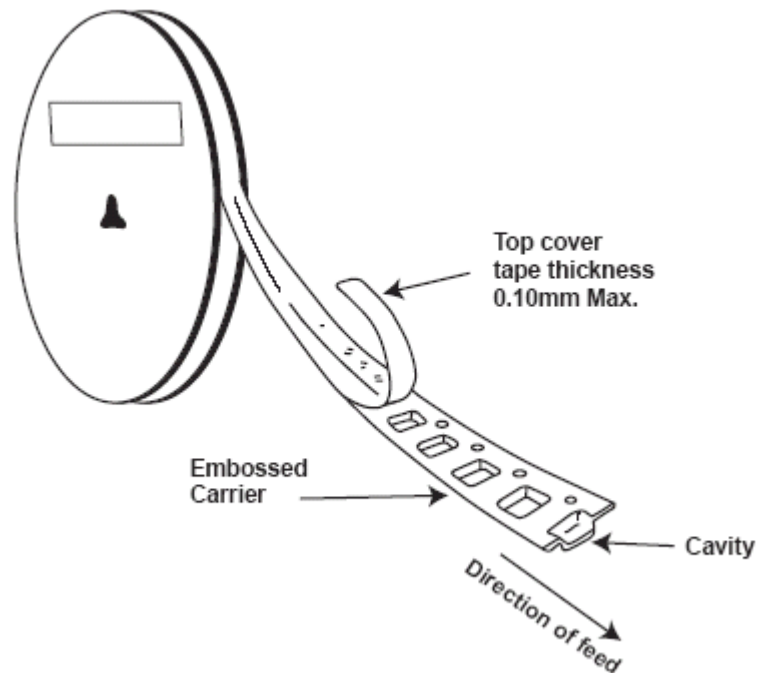
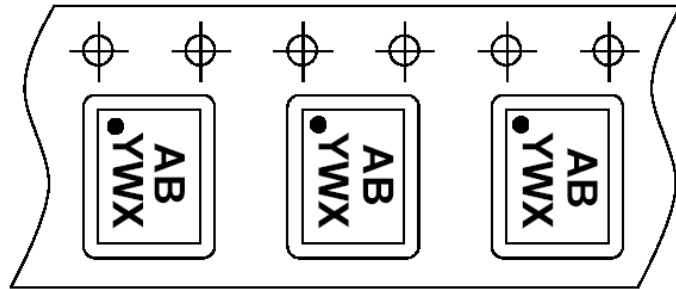
Package Outline Dimensions (All Dimensions in mm)

(3) Package Type: DFN1410



Taping Orientation (Note 7)

For DFN1410



Note: 7. The taping orientation of the other package type can be found on our website at <http://www.diodes.com/datasheets/ap02007.pdf>

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